

Silicon carbide Power MOSFET: 20 A, 1200 V, 189 mΩ (typ., T_J=150 °C), N-channel in a HiP247™

Datasheet - production data

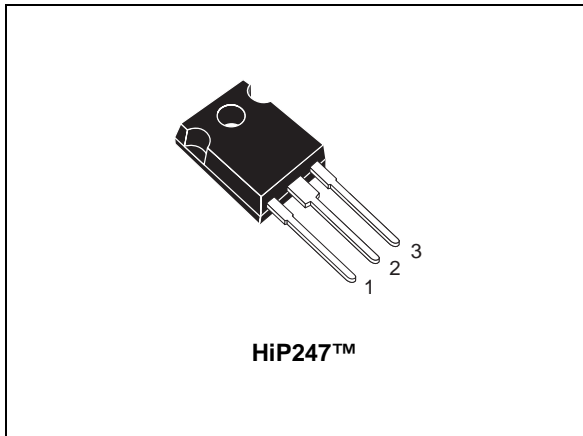
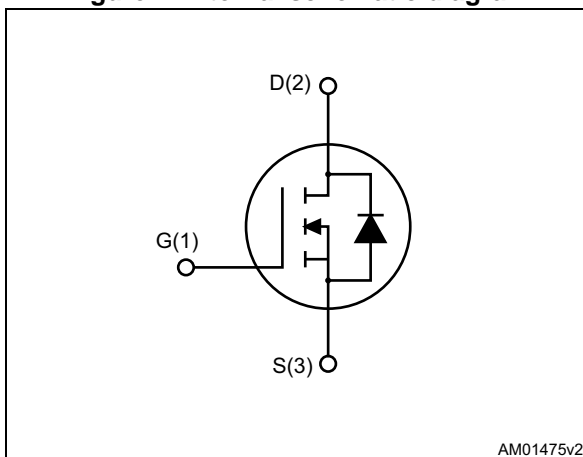


Figure 1. Internal schematic diagram



Features

- Very tight variation of on-resistance vs. temperature
- Slight variation of switching losses vs. temperature
- Very high operating temperature capability (200 °C)
- Very fast and robust intrinsic body diode
- Low capacitance
- Easy to drive

Applications

- Solar inverters, UPS
- Motor drives
- High voltage DC-DC converters
- Switch mode power supplies

Description

This silicon carbide Power MOSFET is produced exploiting the advanced, innovative properties of wide bandgap materials. This results in unsurpassed on-resistance per unit area and very good switching performance almost independent of temperature. The outstanding thermal properties of the SiC material, combined with the device's housing in the proprietary HiP247™ package, allows designers to use an industry-standard outline with significantly improved thermal capability. These features render the device perfectly suitable for high-efficiency and high power density applications.

Table 1. Device summary

| Order code | Marking | Package | Packaging |
|------------|-----------|---------|-----------|
| SCT20N120 | SCT20N120 | HiP247™ | Tube |

Note: The device meets ECOPACK standards, an environmentally-friendly grade of products commonly referred to as "halogen-free". See [Section 4: Package mechanical data](#).

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1 Electrical ratings

Table 2. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|---|------------|------|
| V_{DS} | Drain-source voltage | 1200 | V |
| V_{GS} | Gate-source voltage | -10/+25 | V |
| I_D | Drain current (continuous) at $T_C = 25\text{ °C}$ | 20 | A |
| I_D | Drain current (continuous) at $T_C = 100\text{ °C}$ | 16 | A |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 45 | A |
| P_{TOT} | Total dissipation at $T_C = 25\text{ °C}$ | 175 | W |
| T_{stg} | Storage temperature | -55 to 200 | °C |
| T_j | Operating junction temperature | | °C |

1. Pulse width limited by safe operating area.

Table 3. Thermal data

| Symbol | Parameter | Value | Unit |
|-----------|---|-------|------|
| Rthj-case | Thermal resistance junction-case max | 1 | °C/W |
| Rthj-amb | Thermal resistance junction-ambient max | 40 | °C/W |

2 Electrical characteristics

($T_{CASE} = 25\text{ °C}$ unless otherwise specified).

Table 4. On/off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|--------------|--|--|------|------|------|---------------|
| I_{DSS} | Zero gate voltage drain current ($V_{GS} = 0$) | $V_{DS} = 1200\text{ V}$ | | | 100 | μA |
| | | $V_{DS} = 1200\text{ V}, T_J = 200\text{ °C}$ | | 50 | | μA |
| I_{GSS} | Gate-body leakage current ($V_{DS} = 0$) | $V_{GS} = +22\text{ V} / -10\text{ V}$ | | | 100 | nA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}, I_D = 1\text{ mA}$ | 2 | 3.5 | | V |
| $R_{DS(on)}$ | Static drain-source on-resistance | $V_{GS} = 20\text{ V}, I_D = 10\text{ A}$ | | 169 | 239 | m Ω |
| | | $V_{GS} = 20\text{ V}, I_D = 10\text{ A}, T_J = 150\text{ °C}$ | | 189 | | m Ω |
| | | $V_{GS} = 20\text{ V}, I_D = 10\text{ A}, T_J = 200\text{ °C}$ | | 220 | | m Ω |

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|------------|------------------------------|--|--------------------|------|------|------|
| C_{iss} | Input capacitance | $V_{DS} = 400\text{ V}, f = 1\text{ MHz}, V_{GS} = 0$ | - | 650 | - | pF |
| C_{oss} | Output capacitance | | - | 65 | - | pF |
| C_{riss} | Reverse transfer capacitance | | - | 14 | - | pF |
| Q_g | Total gate charge | $V_{DD} = 800\text{ V}, I_D = 10\text{ A}, V_{GS} = 0 / 20\text{ V}$ | - | 45 | - | nC |
| Q_{gs} | Gate-source charge | | - | 7 | - | nC |
| Q_{gd} | Gate-drain charge | | - | 11.7 | - | nC |
| R_g | Gate input resistance | | f=1 MHz open drain | - | 7 | - |

Table 6. Switching energy (inductive load)

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------|---------------------------|--|------|------|------|---------------|
| E_{on} | Turn-on switching losses | $V_{DD} = 800\text{ V}$, $I_D = 10\text{ A}$ | - | 160 | - | μJ |
| E_{off} | Turn-off switching losses | $R_G = 6.8\ \Omega$, $V_{GS} = -2/20\text{ V}$ | - | 90 | - | μJ |
| E_{on} | Turn-on switching losses | $V_{DD} = 800\text{ V}$, $I_D = 10\text{ A}$ | - | 165 | - | μJ |
| E_{off} | Turn-off switching losses | $R_G = 6.8\ \Omega$, $V_{GS} = -2/20\text{ V}$ $T_J = 150\text{ }^\circ\text{C}$ | - | 100 | - | μJ |

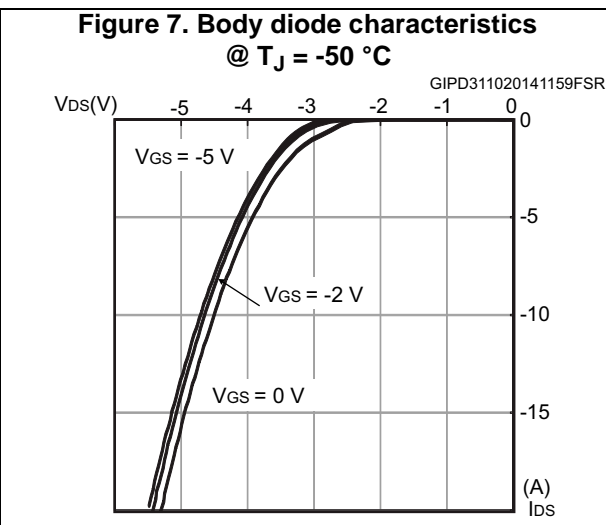
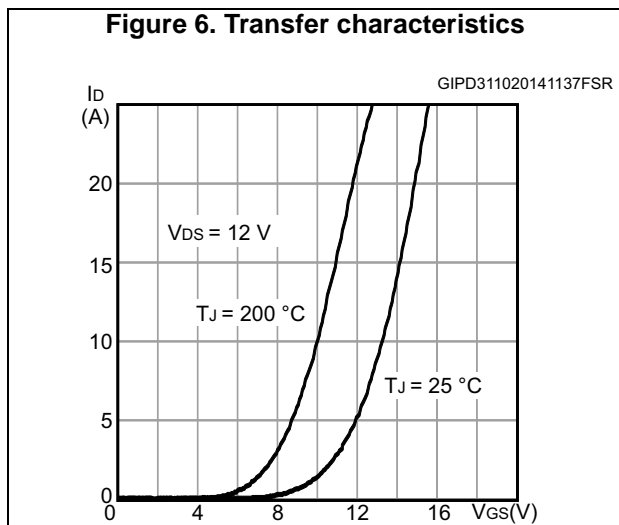
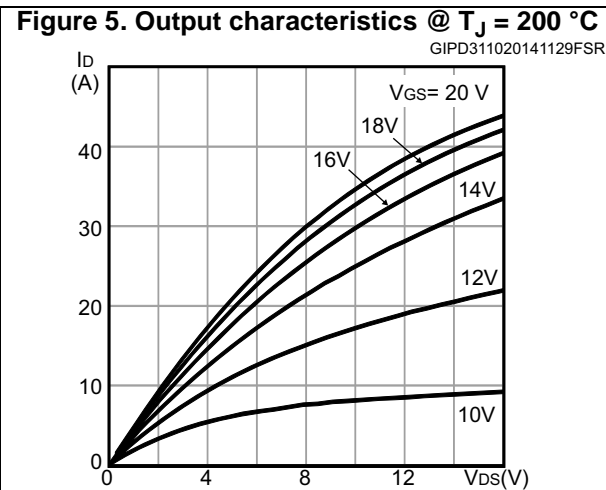
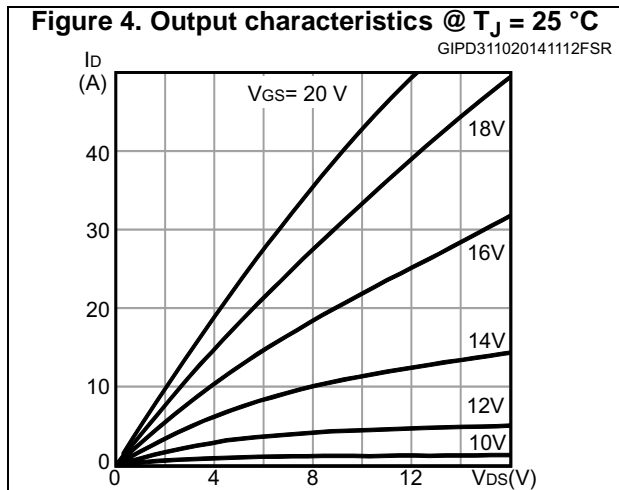
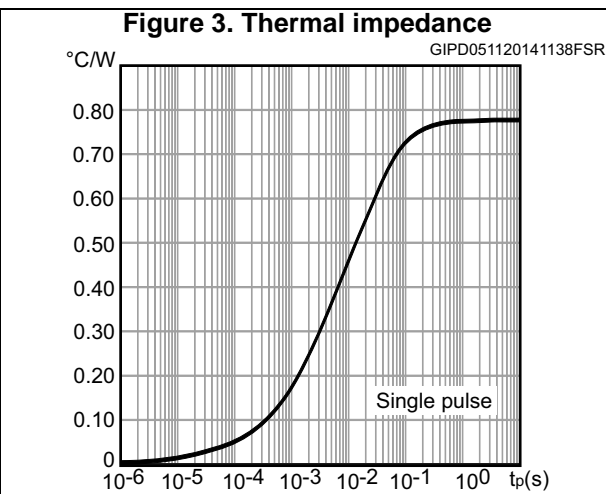
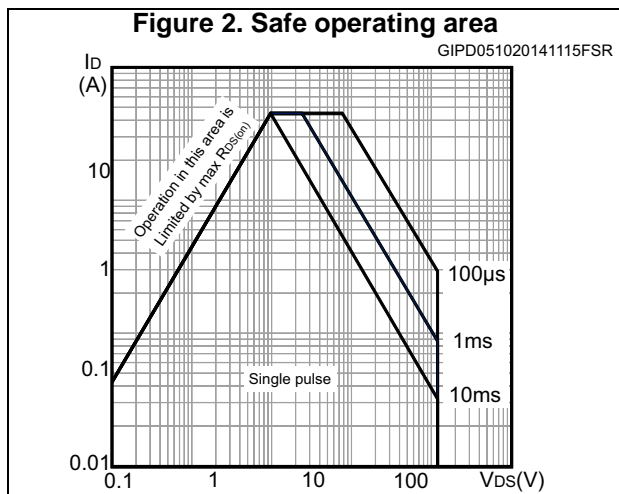
Table 7. Switching times

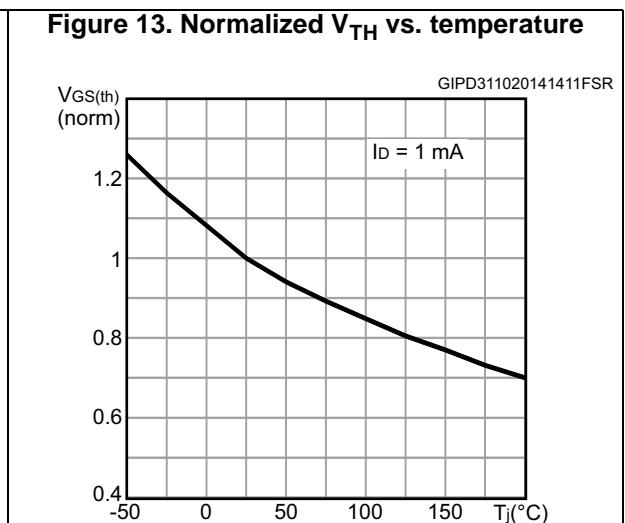
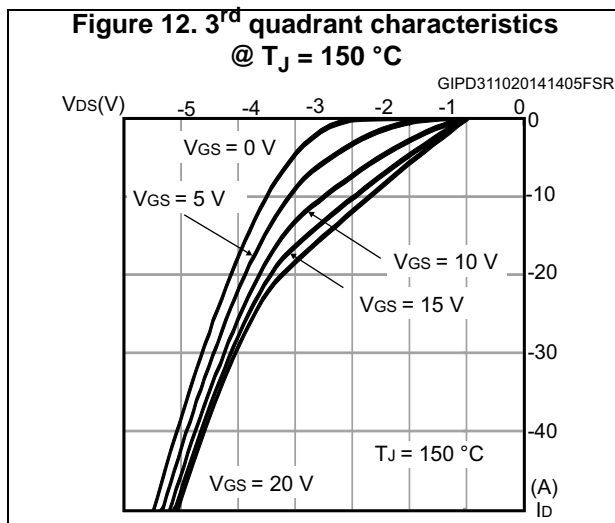
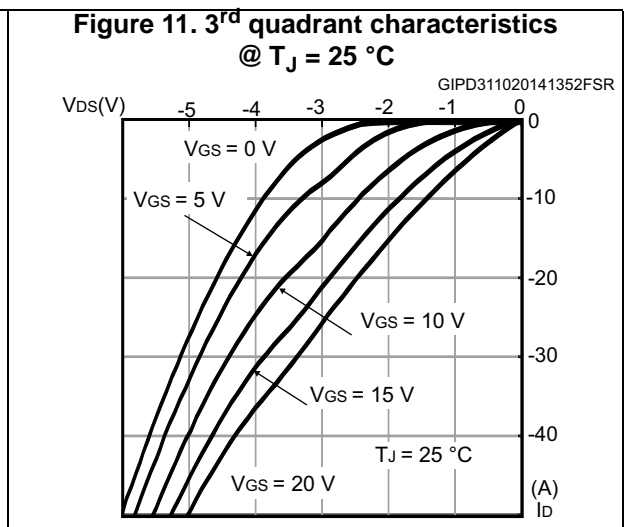
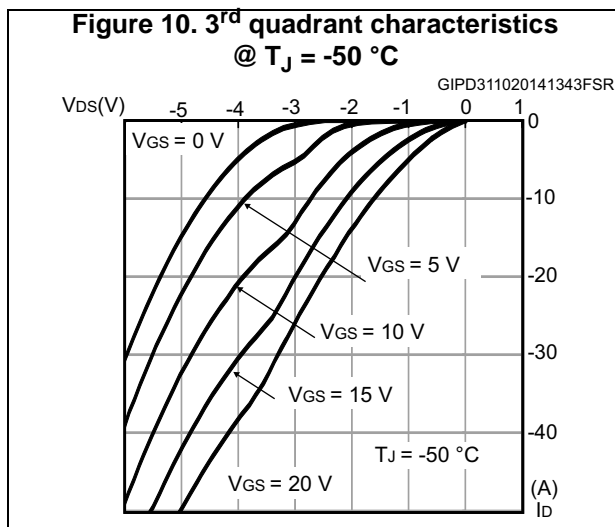
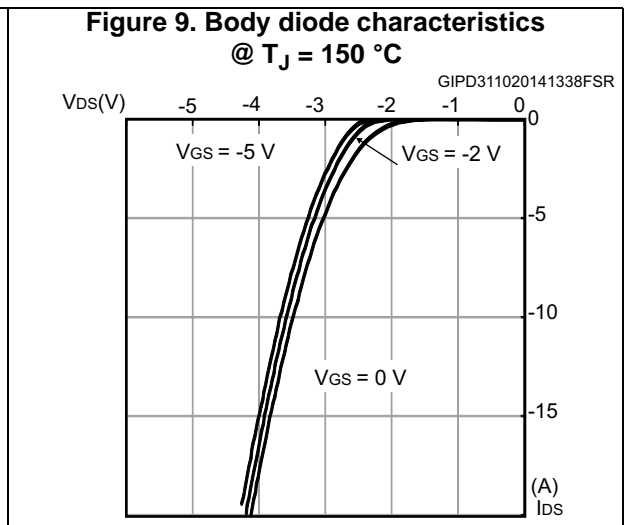
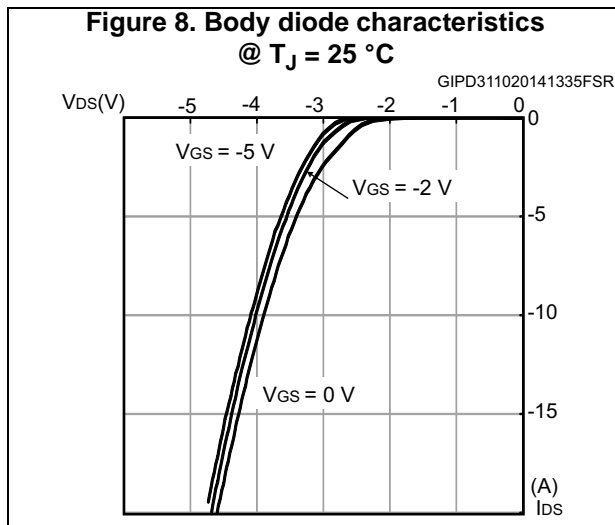
| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|---------------------|---|------|------|------|------|
| $t_{d(on)V}$ | Turn-on delay time | $V_{DD} = 800\text{ V}$, $I_D = 10\text{ A}$, $R_G = 0\ \Omega$, $V_{GS} = 0/20\text{ V}$ | - | 10 | - | ns |
| $t_f(V)$ | Fall time | | - | 17 | - | ns |
| $t_{d(off)V}$ | Turn-off delay time | | - | 27 | - | ns |
| $t_r(V)$ | Rise time | | - | 16 | - | ns |

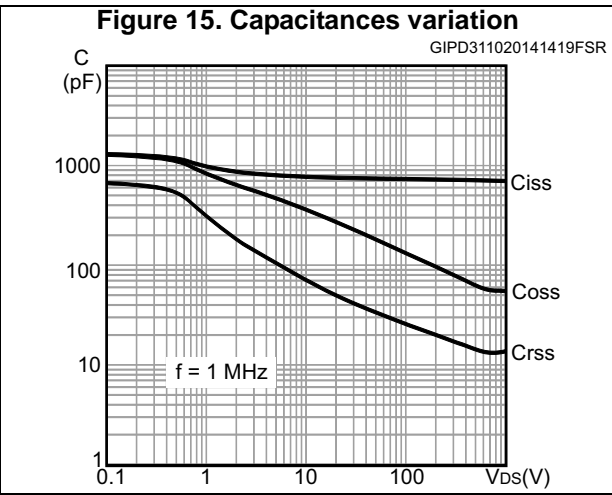
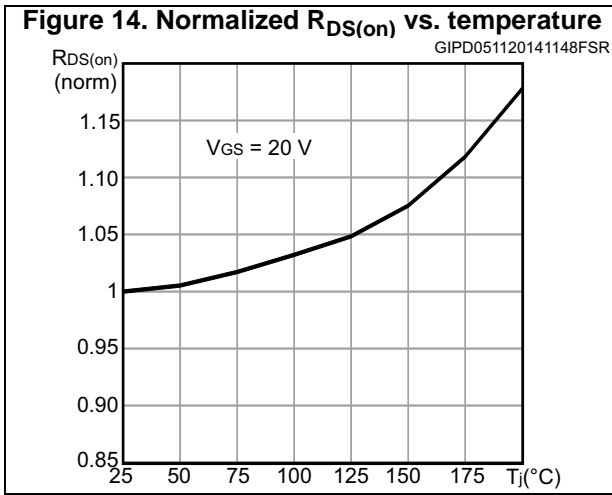
Table 8. Reverse SiC diode characteristics

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------|-------------------------------|---|------|------|------|------|
| V_{SD} | Diode forward voltage | $I_F = 5\text{ A}$, $V_{GS} = -5\text{ V}$ | - | 3.6 | - | V |
| t_{rr} | Reverse recovery time | $I_{SD} = 10\text{ A}$, $V_{GS} = -5\text{ V}$, $V_R = 800\text{ V}$, $dif/dt = 1650\text{ A}/\mu\text{s}$ | - | 15 | - | ns |
| Q_{rr} | Reverse recovery charge | | - | 75 | - | nC |
| I_{rrm} | Peak reverse recovery current | | - | 8 | - | A |

2.1 Electrical characteristics (curves)

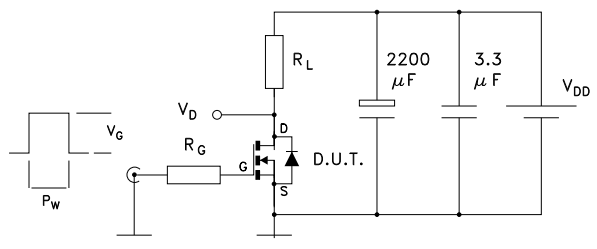






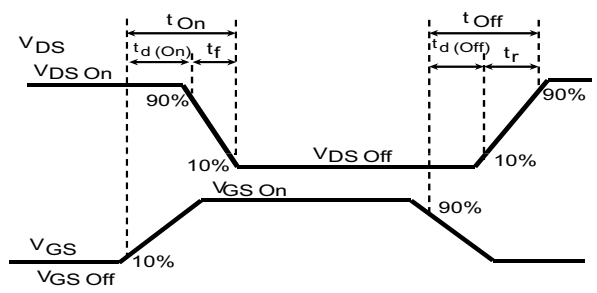
3 Test circuits

Figure 16. Switching test waveforms for transition times



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Figure 17. Clamped inductive switching waveform



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4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Figure 18. HiP247™ drawing

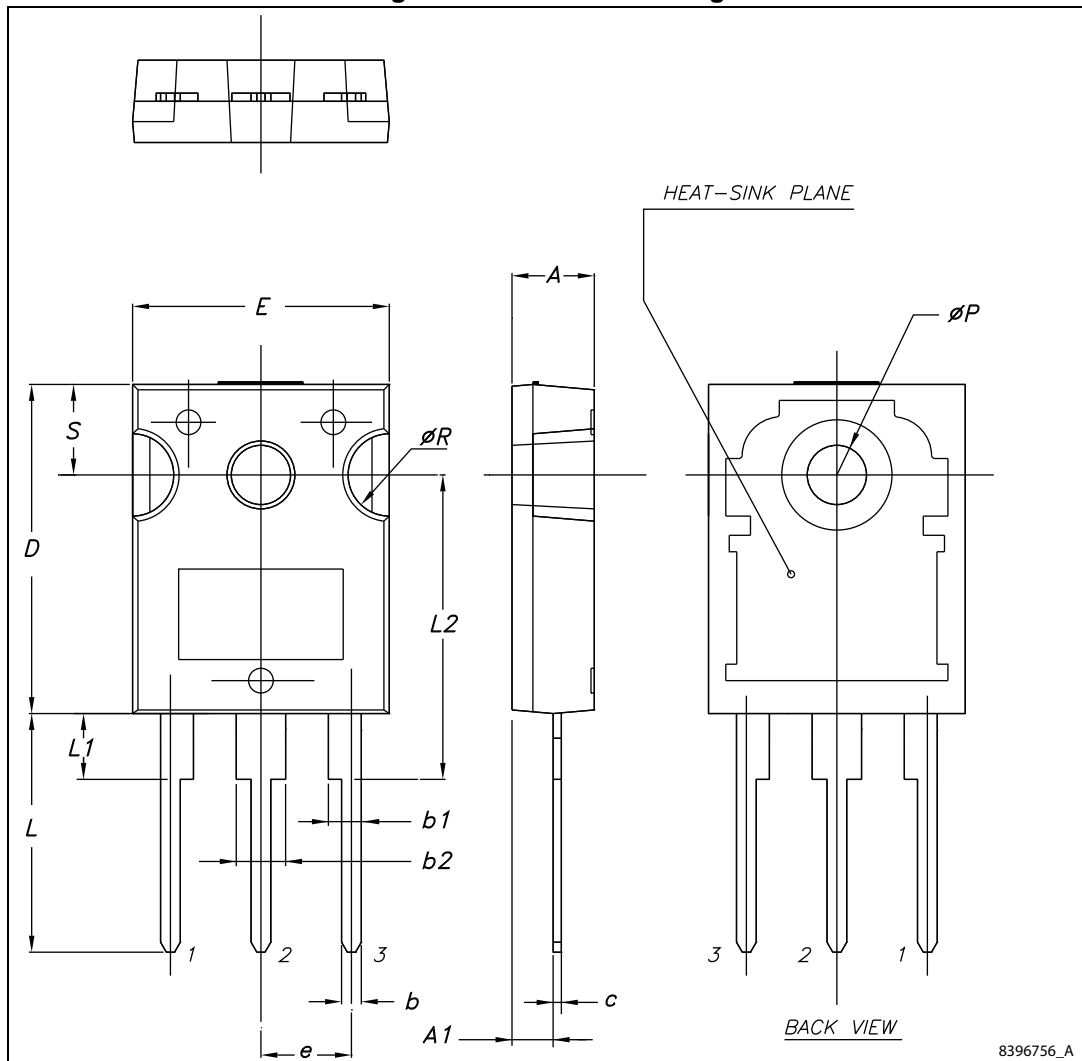


Table 9. HiP247™ mechanical data

| Dim. | mm. | | |
|------|-------|-------|-------|
| | Min. | Typ. | Max. |
| A | 4.85 | | 5.15 |
| A1 | 2.20 | | 2.60 |
| b | 1.0 | | 1.40 |
| b1 | 2.0 | | 2.40 |
| b2 | 3.0 | | 3.40 |
| c | 0.40 | | 0.80 |
| D | 19.85 | | 20.15 |
| E | 15.45 | | 15.75 |
| e | 5.30 | 5.45 | 5.60 |
| L | 14.20 | | 14.80 |
| L1 | 3.70 | | 4.30 |
| L2 | | 18.50 | |
| ØP | 3.55 | | 3.65 |
| ØR | 4.50 | | 5.50 |
| S | 5.30 | 5.50 | 5.70 |

5 Revision history

Table 10. Document revision history

| Date | Revision | Changes |
|-------------|-----------------|--|
| 07-Nov-2014 | 1 | First release |
| 17-Feb-2015 | 2 | Updated title in cover page. |
| 20-Feb-2015 | 3 | Updated Figure 3: Thermal impedance. Minor text changes. |
| 17-Dec-2015 | 4 | Updated title in cover page and Table 4: On/off states . |

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